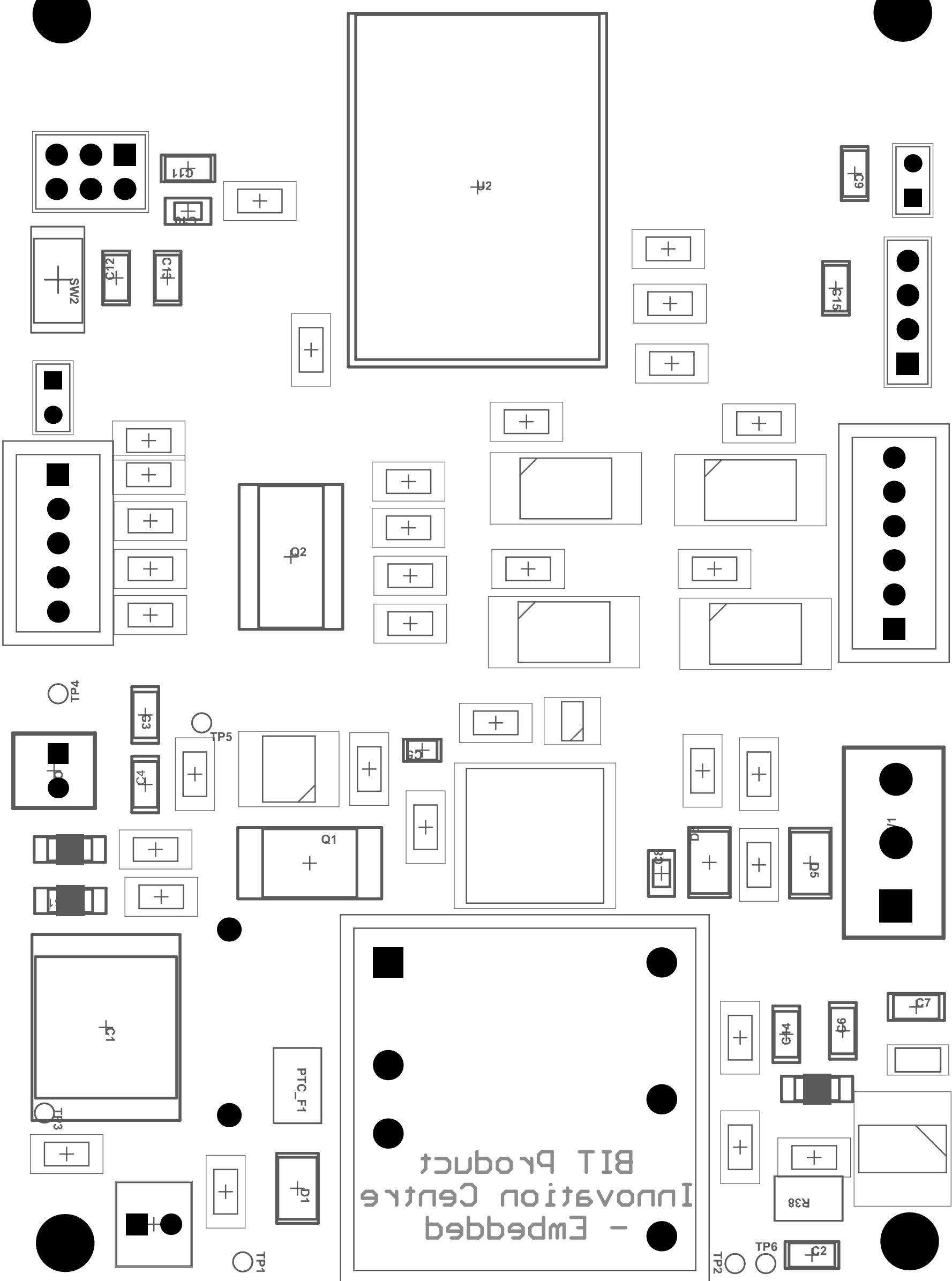
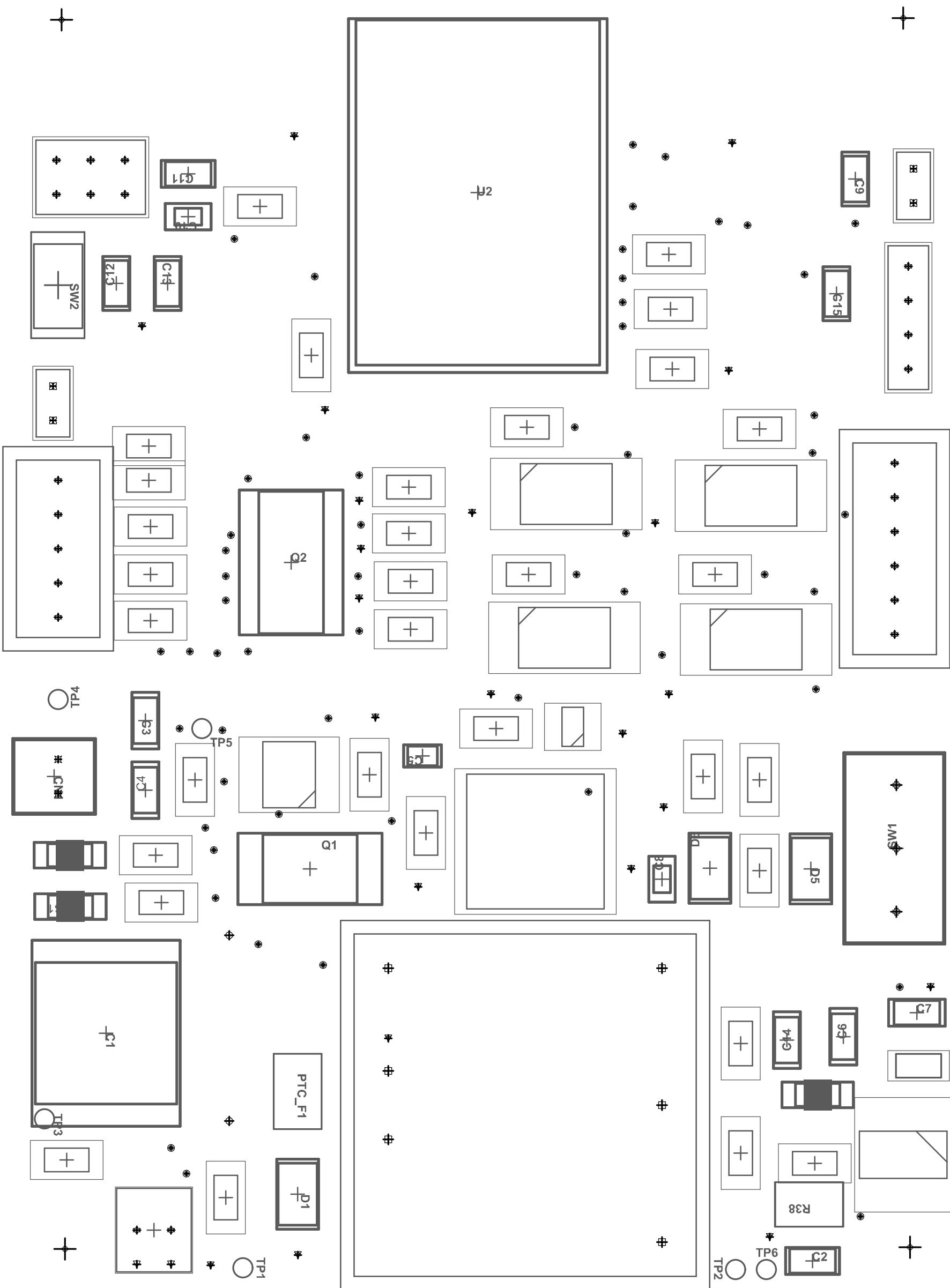


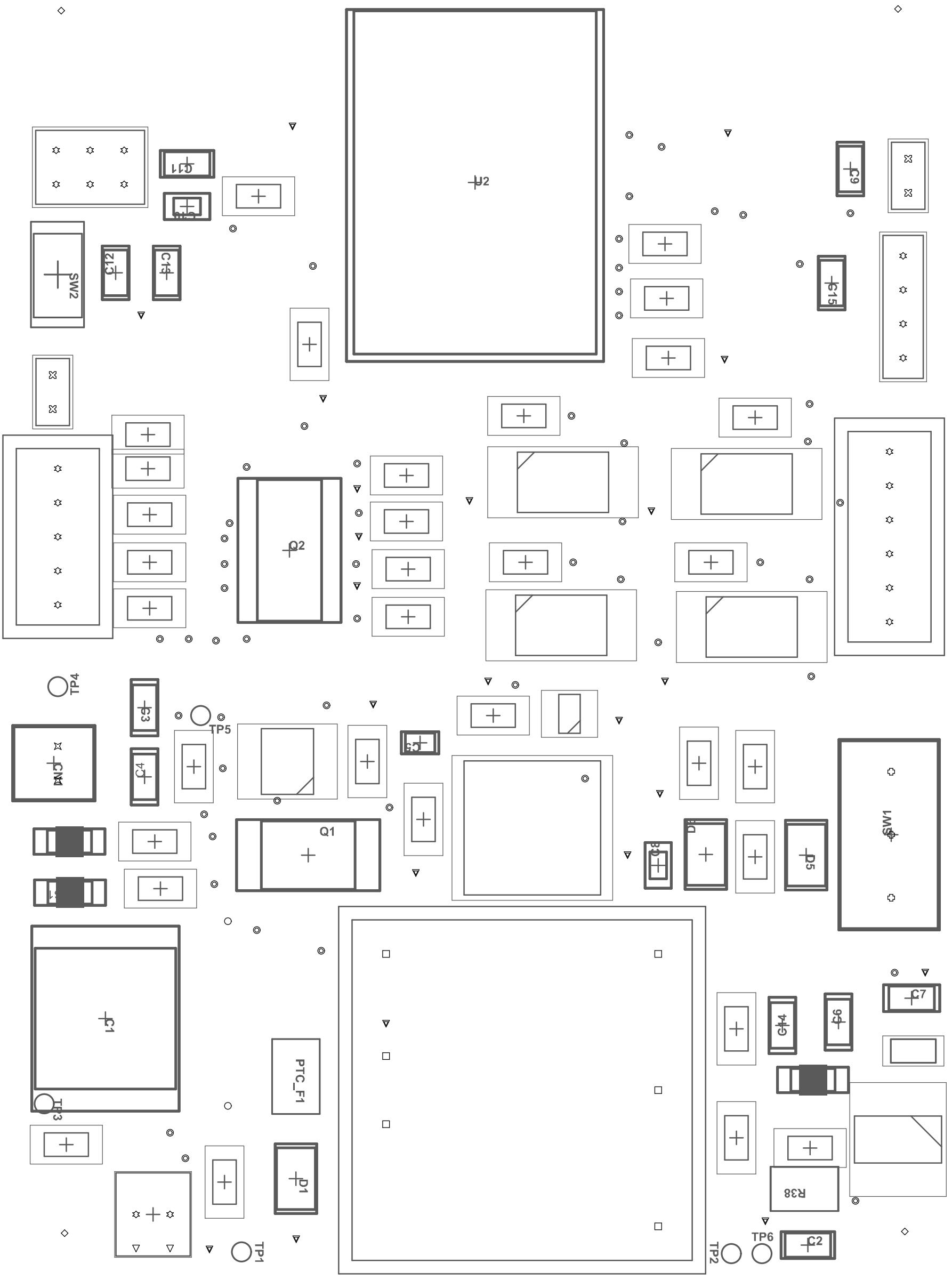
BI Product Innovation Centre - Embedded

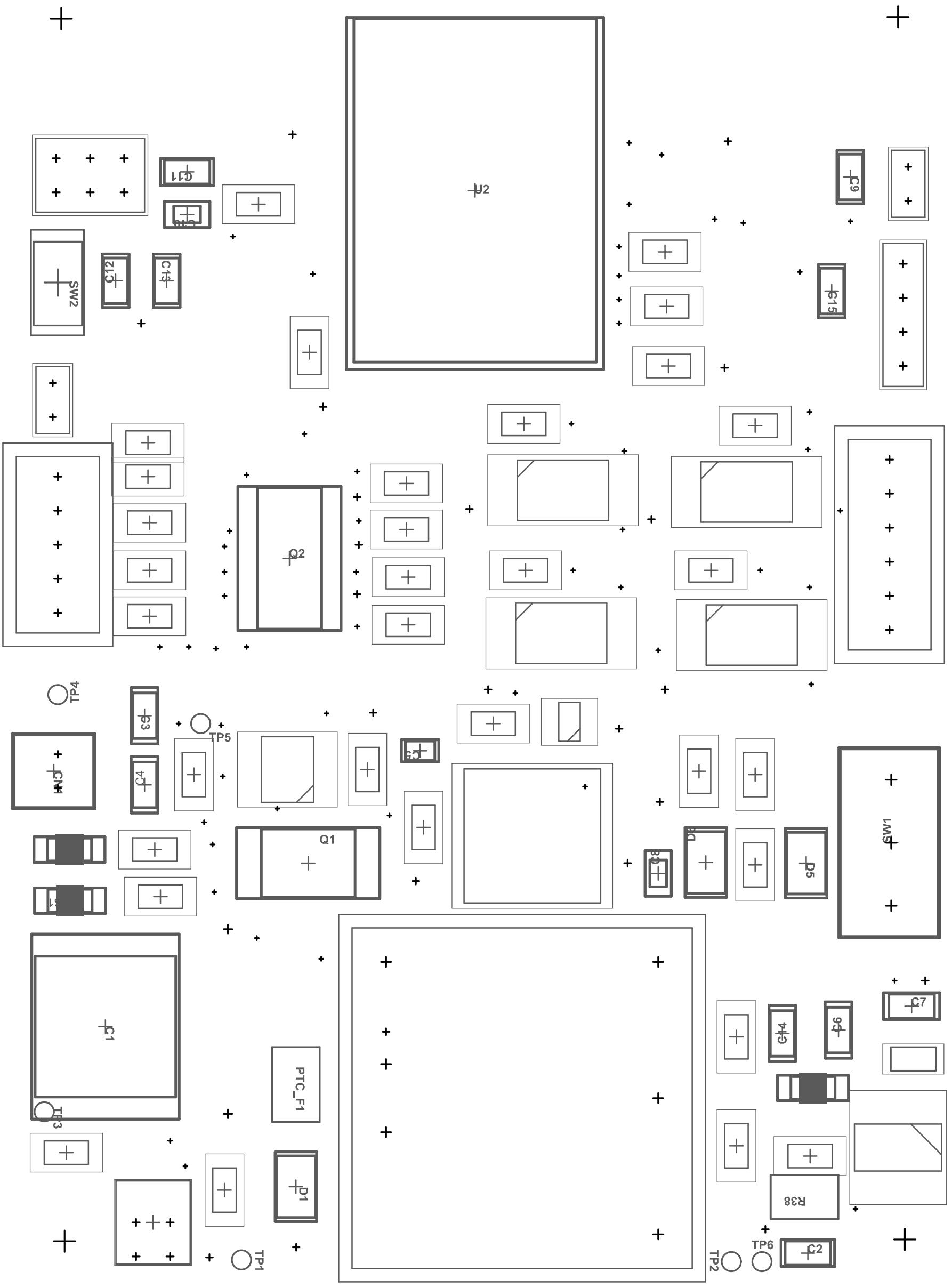


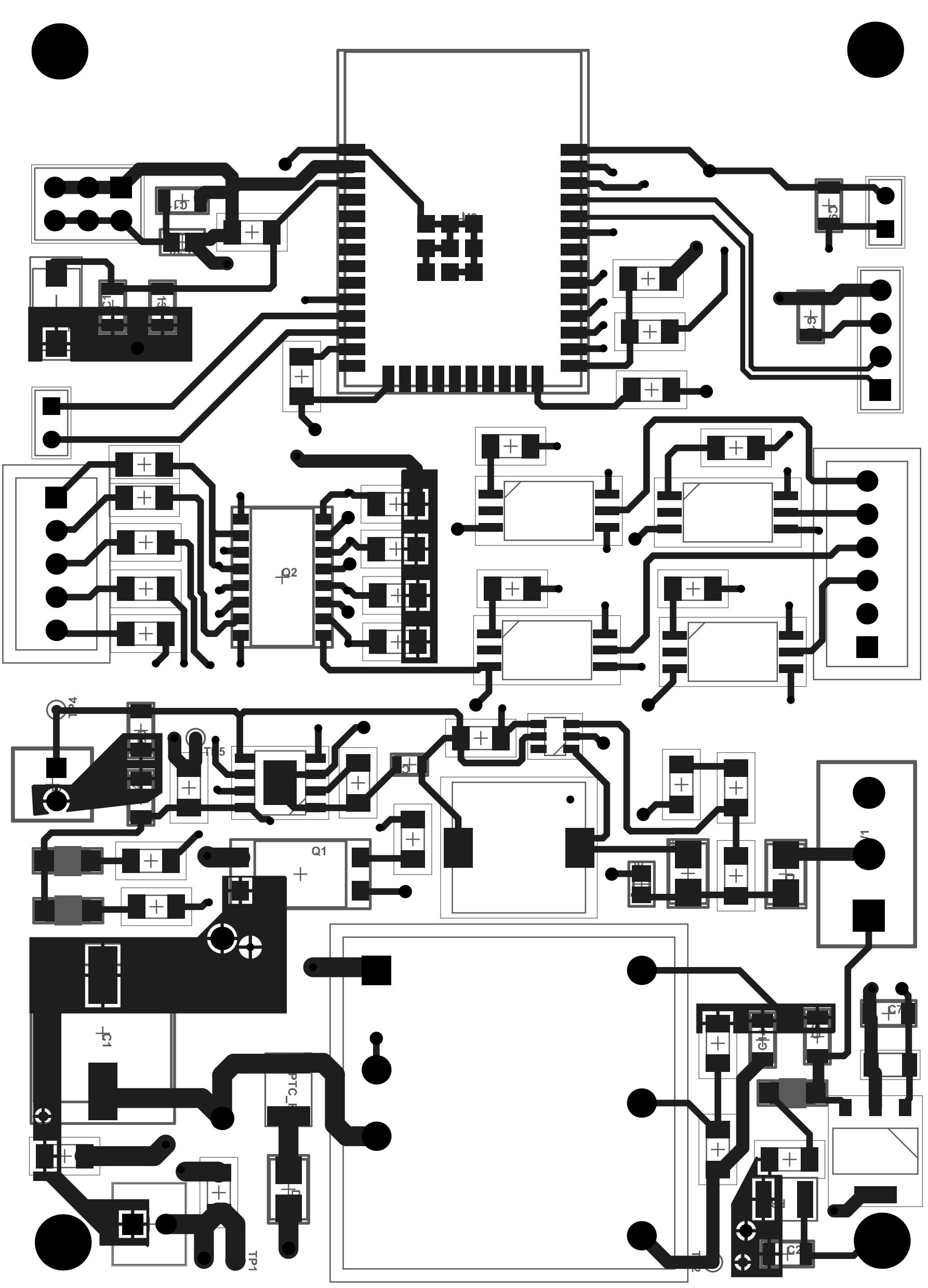
Board Stack Report

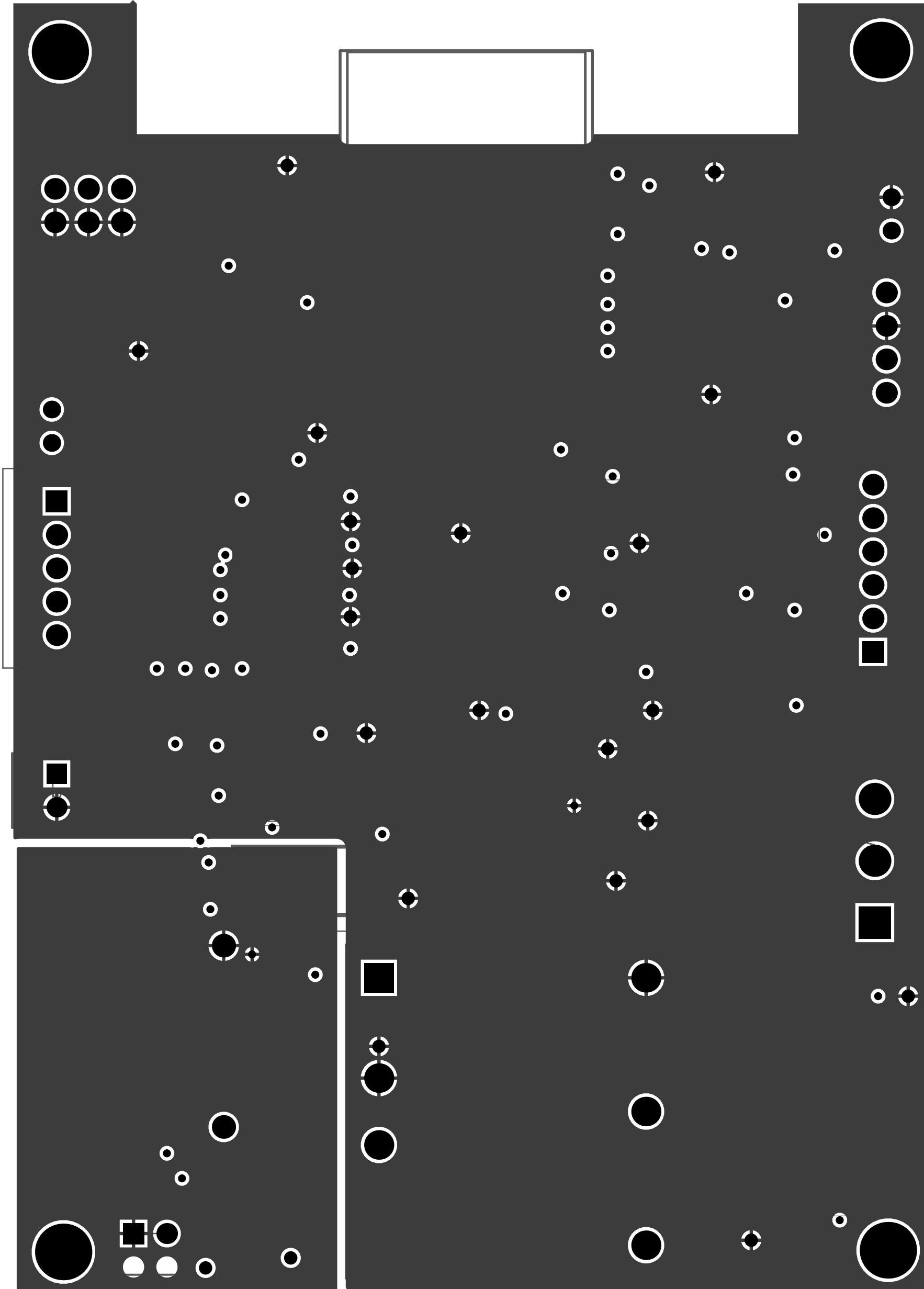
Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		L1_Top Layer	Copper	1.40mil	
5		Dielectric 1	FR-4	2.80mil	4.2
6		L2_GND	Copper	1.42mil	
7		Dielectric 3		39.37mil	4.8
8		L3_VCC	Copper	1.42mil	
9		Dielectric 2	FR-4	2.80mil	4.2
10		Bottom Layer	Copper	1.40mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
	Height : 51.40mil				

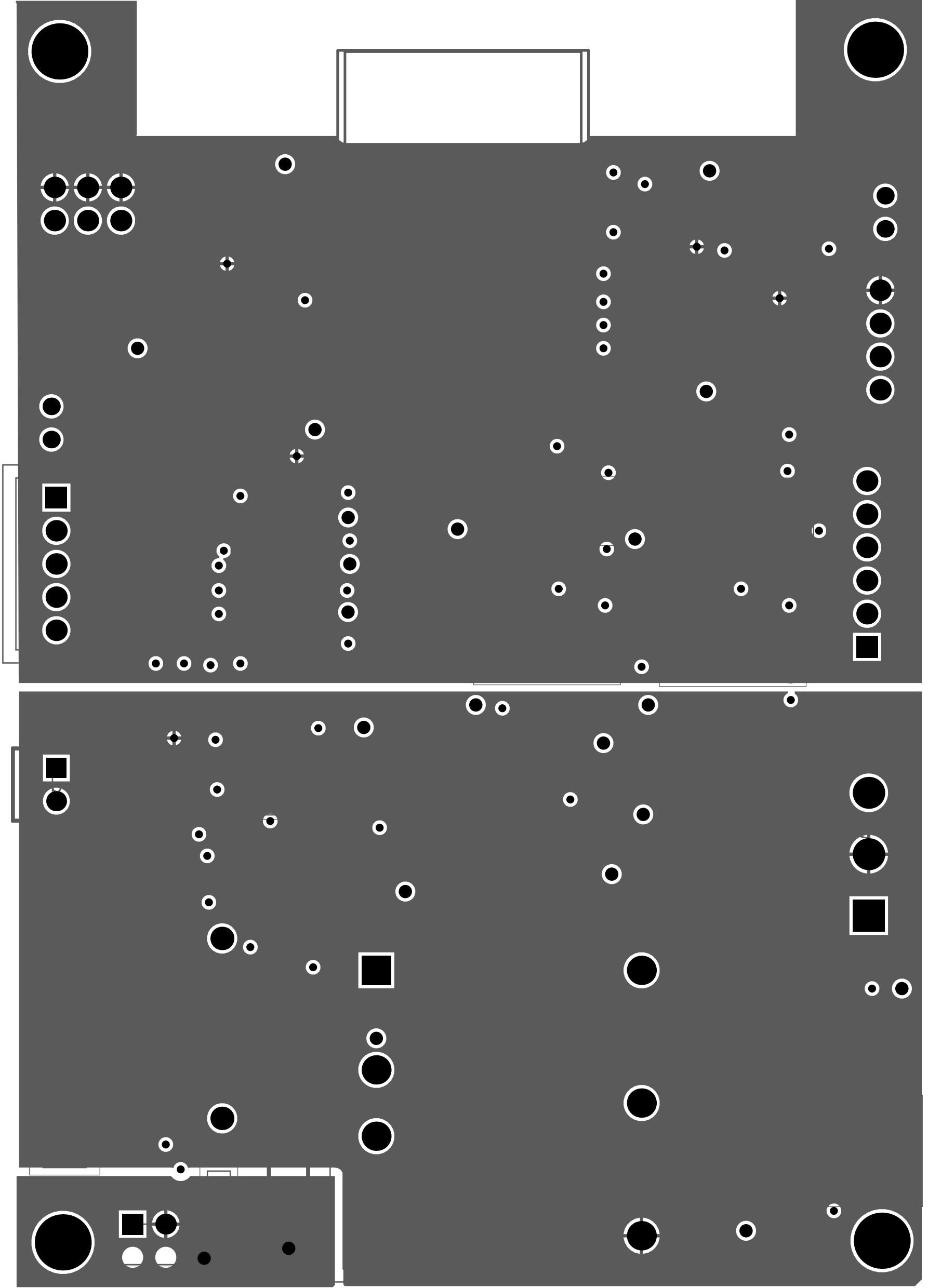


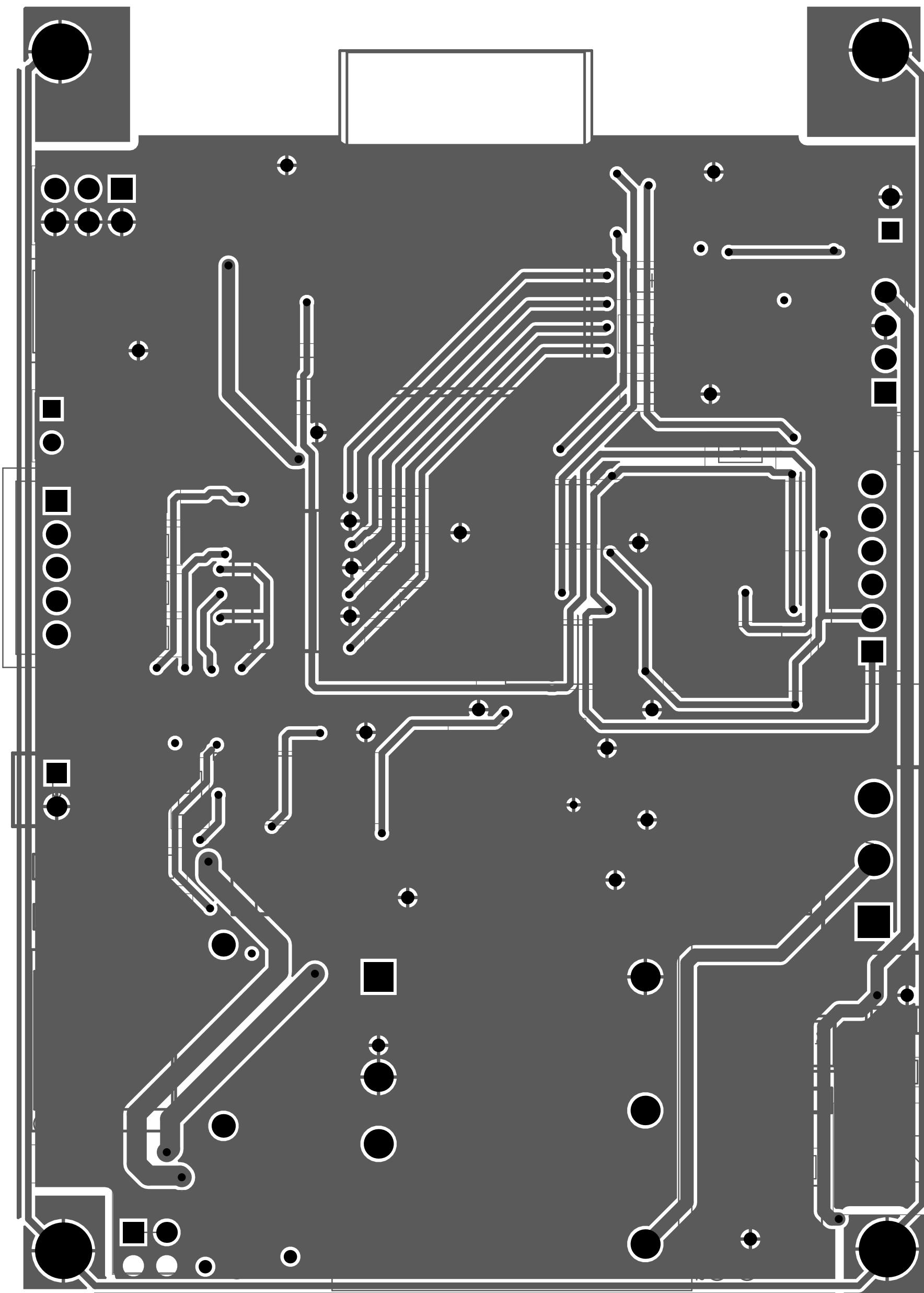


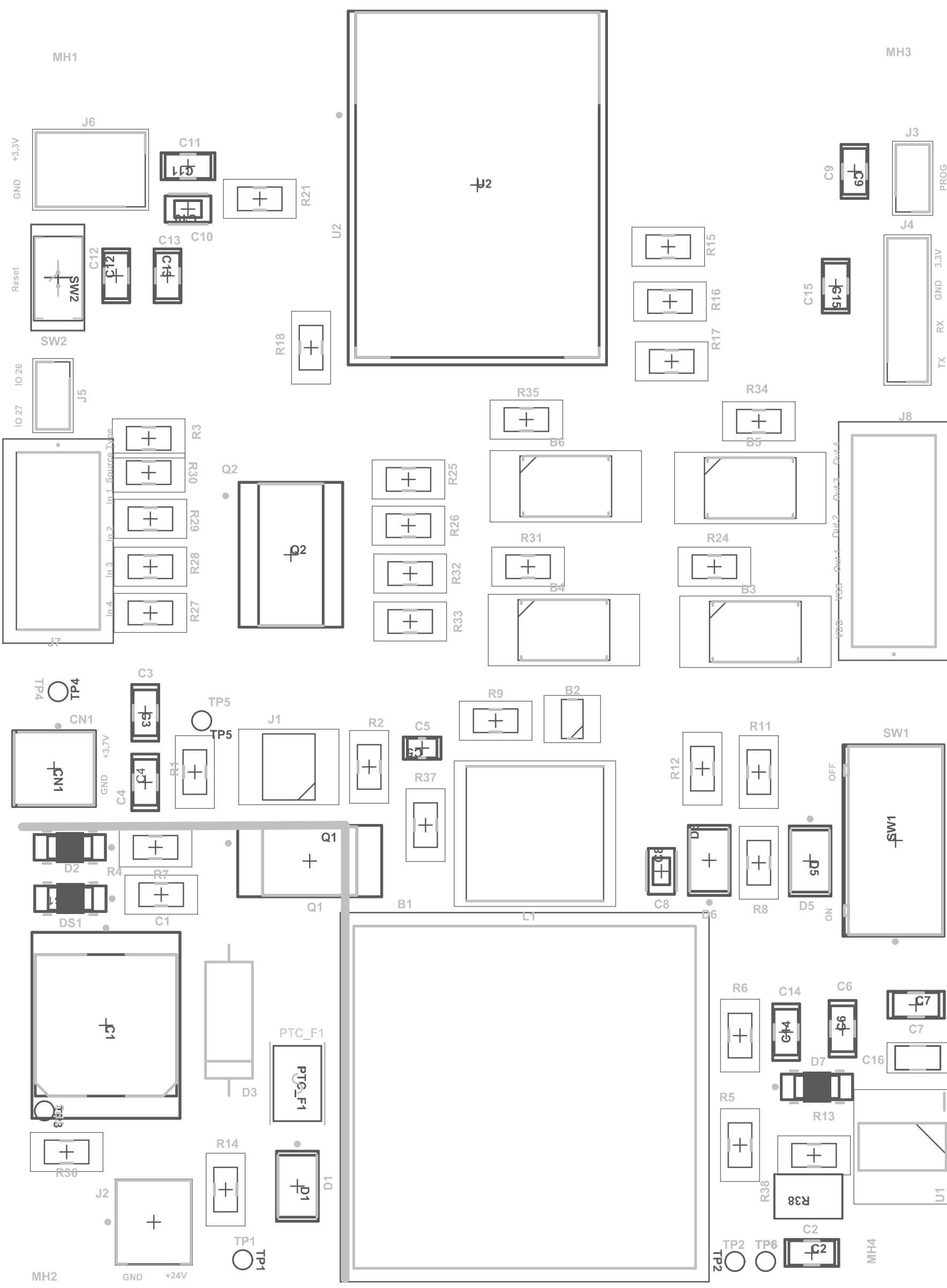












BI Product Innovation Center - Embedded

